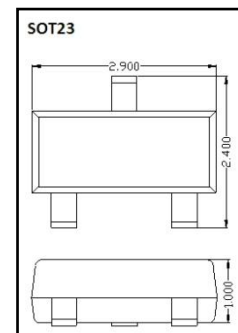


## Schottky Barrier DIODE / DATA SHEET

### BAS70—BAS70-06

- ◇ High Conductance
- ◇ Low Current Leakage
- ◇ Small Outline Surface Mount Package
- ◇ RoHS compliant / Green EMC

MCC Catalog Number	Device Marking	Type	Pin Configuration See page 2
BAS70	73	Single	Figure1
BAS70-04	74	Dual	Figure2
BAS70-05	75	Dual	Figure3
BAS70-06	76	Dual	Figure4

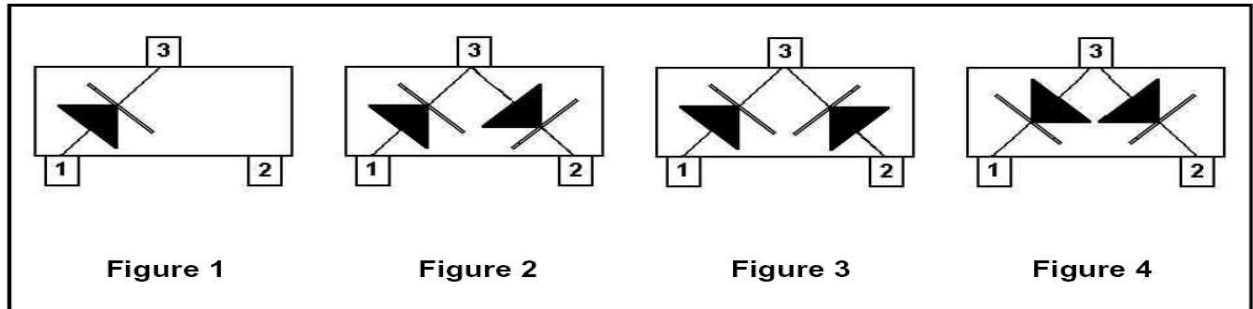


#### MAXIMUM RATINGS (Ta = 25 °C)

Symbol	Parameter	Value	Units
$V_R$	Reverse Voltage	70	V
$I_F$	Forward Continuous Current	70	mA
$P_{tot}$	Power Dissipation	200	mW
$T_J$	Operating Junction Temperature Range	-55 to 125	°C
$I_{FSM}$	Peak Forward Surge Current (t=1S.NON-Repetitive)	0.1	A
$T_{stg}$	Storage Temperature Rance	-55 to 150	°C
$T_J$	Soldering temperature during	260	°C
$R_j$	Thermal Resistance Junction to Ambient	430	°C/W

#### ELECTRICAL CHARACTERISTICS (Ta = 25 °C)

Symbol	Parameter	Test Conditions	Min	Max	Units
$V_F$	Forward Voltage	$I_F=1mA$ $I_F=15mA$		0.41 1.0	V
$V_R$	Reverse breakdown voltage	$I_R=10uA$	70		V
$I_R$	Reverse voltage leakage current	$V_R=50V$		200	nA
$C_J$	Typical Junction Capacitance	$V_R=0V, f=1.0MHz$		2	pF
$T_{rr}$	Reverse recovery time	$I_F=I_R=10mA, I_{(REG)}=1mA$		5	nS

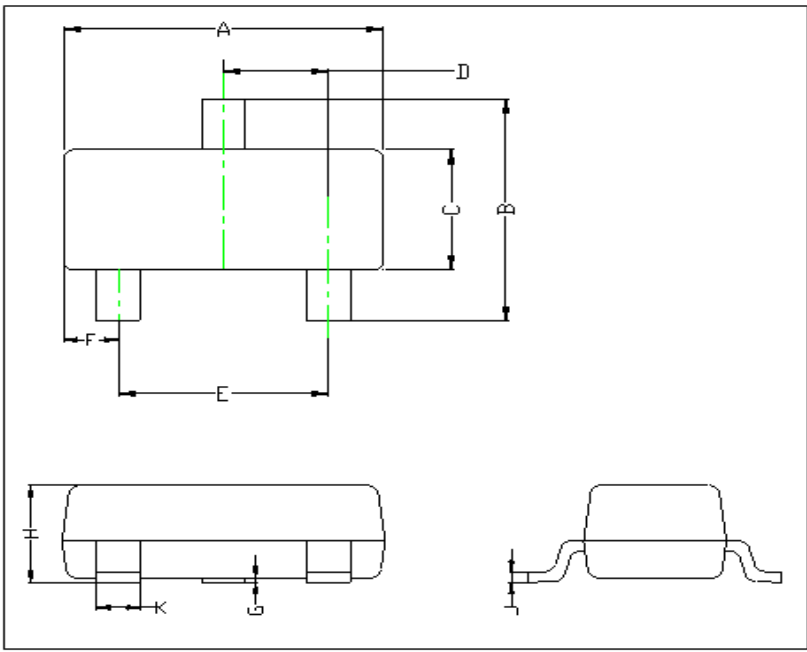


**ORDERING INFORMATION**

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
BAS70---- BAS70-06	SOT23	Tape & Reel 3000pcs /7" Reel	8mm	4mm	Conductive	

**PACKAGE DIMENSIONS**

**Package Outline : SOT23**



Symbol	Dimensions in mm	
	Min.	Max.
A	2.800	3.040
B	2.100	2.640
C	1.200	1.400
D	0.890	1.030
E	1.780	2.050
F	0.450	0.600
G	0.013	0.100
H	0.900	1.110
J	0.090	0.180
K	0.370	0.510

**Note:**  
 1. Halogen free ,EMC  
 2. Pb free solder  
 3: Lead thickness solder plating  
 4. Lead frame CAC-5  
 5. Other Tolerance  $\pm 0.05$   
 6. Dimensions are exclusive of Burrs Mold Flash and Tie Bar extrusions  
 7. Unit : mm

**SOT23 Package Outline**